IMPACTS OF (ZERO) TRUST IN DOD MICROELECTRONICS TO COMMERCIAL INDUSTRY WORKSHOP

September 9 – 10, 2021 | NDIA.org/ZeroTrustWorkshop
WHO WE ARE
The National Defense Industrial Association is the trusted leader in defense and national security associations. As a 501(c)(3) corporate and individual membership association, NDIA engages thoughtful and innovative leaders to exchange ideas, information, and capabilities that lead to the development of the best policies, practices, products, and technologies to ensure the safety and security of our nation. NDIA’s membership embodies the full spectrum of corporate, government, academic, and individual stakeholders who form a vigorous, responsive, and collaborative community in support of defense and national security. For more than 100 years, NDIA and its predecessor organizations have been at the heart of the mission by dedicating their time, expertise, and energy to ensuring our warfighters have the best training, equipment, and support. For more information, visit NDIA.org

ELECTRONICS DIVISION
WHO WE ARE
The Electronics Division leads the evaluation of current and future challenges while developing proposed solutions to such challenges so that government and industry may access trusted and assured electronics. The Division provides for the exchange of information between the defense and commercial industries, universities, research centers, standards bodies, and government and military representatives on technology spanning advanced R&D, design, manufacturing, and the deployment of defense and national security systems.

LEADERSHIP AND COMMITTEES
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Committee Member, Electronics Division

SPEAKER GIFTS
In lieu of speaker gifts, a donation is being made to the Fisher House Foundation.

HARASSMENT STATEMENT
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REAL-TIME Q&A
Sli.do is an audience engagement platform that allows users to crowd-source top questions to drive meaningful conversations and increase crowd participation. Participants can up-vote the questions they would most like to hear discussed. Simply tap the thumbs-up button to up-vote a question. Top questions are displayed for the moderator and speaker to answer. Ask your question in sessions by going to Sli.do!

Event code: #Electronics2021
AGENDA

THURSDAY, SEPTEMBER 9

10:00 – 10:20 am
INTRODUCTION
Dr. Devenand Shenoy
Principal Director, Microelectronics, Office of the Under Secretary of Defense for Research & Engineering
Arsenio (Bong) Gumahad II
Director, Command, Control, Communications, Computers, Intelligence, Surveillance, & Reconnaissance (C4ISR), Office of the Deputy Assistant Secretary of Defense for Acquisition

10:20 – 10:45 am
MAIN MANUAL
Dr. Linton Salmon
Principal Technical Advisor to the Principal Director for Microelectronics, Office of the Under Secretary of Defense for Research & Engineering

10:45 – 11:10 am
LEVELS OF ASSURANCE
Gregory Murphy
Senior Technical Leader, Joint Federated Assurance Center (NSA)

11:10 – 11:25 am
BREAK

11:25 – 11:50 am
ATTACK COUNTERMEASURE ANALYSIS (ACMA)
Christine Rink
Senior Project Leader, The Aerospace Corporation

11:50 am – 12:15 pm
CUSTOM IC STANDARD (DESIGN/PERSONALIZATION)
Christine Rink
Senior Project Leader, The Aerospace Corporation

12:15 – 12:40 pm
CUSTOM IC STANDARD (FOUNDRY, MASK, ASSEMBLY, TEST)
Dr. Linton Salmon
Principal Technical Advisor to the Principal Director for Microelectronics, Office of the Under Secretary of Defense for Research & Engineering

12:40 – 1:30 pm
FPGA STANDARD
Gregory Murphy
Senior Technical Leader, Joint Federated Assurance Center (NSA)

1:30 – 2:00 pm
BREAK

2:00 – 3:30 pm
Q&A SESSION 1

3:30 – 4:00 pm
BREAK

4:00 – 5:30 pm
Q&A SESSION 2

FRIDAY, SEPTEMBER 10

10:00 – 11:30 am
Q&A SESSION 3

11:30 am – 1:00 pm
BREAK

1:00 – 2:30 pm
Q&A SESSION 4

2:30 – 3:00 pm
BREAK

3:00 – 4:30 pm
Q&A SESSION 5

NDIA has a policy of strict compliance with federal and state antitrust laws. The antitrust laws prohibit competitors from engaging in actions that could result in an unreasonable restraint of trade. Consequently, NDIA members must avoid discussing certain topics when they are together at formal association membership, board, committee, and other meetings and informal contacts with other industry members: prices, fees, rates, profit margins, or other terms or conditions of sale (including allowances, credit terms, and warranties); allocation of markets or customers or division of territories; or refusals to deal with or boycotts of suppliers, customers or other third parties, or topics that may lead participants not to deal with a particular supplier, customer or third party.

AN ONLINE COMMUNITY FOR DEFENSE PROFESSIONALS

NDIA Connect is a members-only benefit that’s bustling with information, conversation, and activity stimulated by defense professionals from industry, government, and academia. Log in today to explore the platform’s various functionalities and contribute to our collective mission in support of the warfighter. From anywhere and at any time, use NDIA Connect to network with colleagues, collaborate on projects, and stay connected.

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In this capacity, Dr. Salmon initiated and managed programs in integrated circuit design (CRAFT), hardware security (SSITH), Monolithic 3-D Technology (3D-SoC), and a joint government/industry program to drive microelectronics research in universities (JUMP). Prior to joining DARPA, Dr. Salmon spent 15 years in executive roles directing development of CMOS technology from the 130nm node through the 7nm node at Texas Instruments, Advanced Micro Devices, and GlobalFoundries. He focused on technology enablement, design/technology interaction, and ramping of developed technology into production in 300mm water fabrication factories in the United States, Europe, and Asia.

Prior to joining AMD, Dr. Salmon was Vice President for Research and Technology Transfer at Case Western Reserve University, interfacing between faculty and external entities in the commercialization of university-led research. Prior to CWRU, Dr. Salmon was associate professor of electrical engineering and physics and Associate Dean of Engineering at Brigham Young University where his research areas included CMOS processes, micro-battery research, advanced packaging, and MEMS.

Dr. Linton Salmon
Principal Technical Advisor to the Principal Director for Microelectronics
Office of the Undersecretary of Defense for Research & Engineering

Dr. Linton Salmon currently serves as the Principal Technical Advisor to the Principal Director for Microelectronics in Office of the Undersecretary of Defense for Research and Engineering (USD(R&E)). In this role, Dr. Salmon provides technical support for the DoD Microelectronics strategy, including technical guidance for key programs such as SHIP, RAMP-C, and RAMP-G. Dr. Salmon also leads the team establishing the Quantifiable Assurance (QA) method to provide supply chain assurance for DoD microelectronic components and leads drafting of the standards required to implement QA.

Prior to serving as a technical advisor in USD(R&E), Dr. Salmon served as program manager in the MTO office at DARPA. In this capacity, Dr. Salmon initiated and managed programs in integrated circuit design (CRAFT), hardware security (SSITH), Monolithic 3-D Technology (3D-SoC), and a joint government/industry program to drive microelectronics research in universities (JUMP). Prior to joining DARPA, Dr. Salmon spent 15 years in executive roles directing development of CMOS technology from the 130nm node through the 7nm node at Texas Instruments, Advanced Micro Devices, and GlobalFoundries. He focused on development of semiconductor processes, technology enablement, design/technology interaction, and ramping of developed technology into production in 300mm water fabrication factories in the United States, Europe, and Asia. Prior to joining AMD, Dr. Salmon was Vice President for Research and Technology Transfer at Case Western Reserve University, interfacing between faculty and external entities in the commercialization of university-led research. Prior to CWRU, Dr. Salmon was associate professor of electrical engineering and physics and Associate Dean of Engineering at Brigham Young University where his research areas included CMOS processes, micro-battery research, advanced packaging, and MEMS.

Dr. salmon began his career directing development of II-V materials and processes for DoD and commercial applications at Hughes Research Laboratories and Rockwell International. Dr. Salmon earned his B.S. in Physics at Stanford University and his M.S. and PhD in Applied and Engineering Physics at Cornell University.